



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-03-25
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MQ0V*U1C0AD5	A	Z6HA	2014-03-25
Amount	UoM	Unit type	ST ECOPACK Grade	
17.90	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	3X2X0.9	8	gull wing	
Comment	Package: VFQFPN 8 2x3x0.9 PITCH 0.5; MDF valid for ST1L08PUR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MQOV*U1C0AD5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.613	mg	supplier	die	Silicon (Si)	7440-21-3		0.575	mg	938010	32123
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.008	mg	13051	447
Silicon die				supplier	metallization	Tungsten (W)	7440-33-7		0.007	mg	11419	391
Silicon die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	3263	112
Silicon die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.014	mg	22838	782
Silicon die				supplier	passivation	Gamma-butyrolactone	96-48-0		0.005	mg	8157	279
Silicon die				supplier	passivation	Polyhydroxyamide	55295-98-2		0.002	mg	3263	112
Lead frame	Copper & its alloys	6.753	mg	supplier	Alloy	Copper (Cu)	7440-50-8		6.522	mg	965793	364358
Lead frame				supplier	Alloy	Iron (Fe)	7439-89-6		0.152	mg	22509	8492
Lead frame				supplier	Alloy	Phosphorus (P)	12185-10-3		0.002	mg	296	112
Lead frame				supplier	Alloy	Zinc (Zn)	7440-66-6		0.009	mg	1333	503
Lead frame				supplier	Alloy	Silver (Ag)	7440-22-4		0.068	mg	10070	3799
Die attach	Other inorganic materials	0.133	mg	supplier	glue	Silver (Ag)	7440-22-4		0.091	mg	684211	5084
Die attach				supplier	glue	methylene diacrylate	42594-17-2		0.033	mg	248120	1844
Die attach				supplier	glue	Dicyclopentenyl ethyl methacrylate	68586-19-6		0.004	mg	30075	223
Die attach				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.004	mg	30075	223
Die attach				supplier	glue	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.001	mg	7519	56
Bonding wire	Other inorganic materials	0.142	mg	supplier	wire	Copper(Cu)	7440-50-8		0.142	mg	1000000	7933
encapsulation	Other inorganic materials	9.87	mg	supplier	mold compound	Silica, vitreous	60676-86-0		9.248	mg	936981	516648
encapsulation				supplier	mold compound	epoxy resin	85954-11-6		0.296	mg	29990	16536
encapsulation				supplier	mold compound	phenol resin	26834-02-6		0.296	mg	29990	16536
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.03	mg	3040	1676
connections coating	Solder	0.389	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.389	mg	1000000	21732